

EAST Search History

EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--------------|---|------------------|---------|---------------------|
| L1 | 119 | 257/E23.067 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 15:32 |
| L2 | 132 | 257/E23.068 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 15:32 |
| L3 | 3339 | 257/48 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 15:34 |
| L4 | 6102 | 257/666 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 15:39 |
| L5 | 2147 | 349/117 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 15:59 |
| L6 | 6204 | 428/403 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 16:15 |
| L7 | 1236 | 75/255 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 16:30 |

| | | | | | | |
|-----|------|--|---|----|-----|---------------------|
| L8 | 374 | 362/458 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 16:37 |
| L9 | 17 | (semiconductor or die or dice or chip or Ic) and (copper or "Cu") with (bump or pad or electrode) and (copper or "Cu") with "10" near (microns or micrometer or "mu. m") and solder with "40" near (microns or micrometer or "mu. m") | USPAT | OR | OFF | 2009/09/25 17:13 |
| L10 | 4883 | 362/800 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 17:59 |
| L11 | 3804 | 439/66 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 18:10 |
| L12 | 1396 | 439/91 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 18:37 |
| L13 | 8806 | 324/765 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 19:06 |
| L14 | 2216 | 324/761 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 19:20 |

| | | | | | | |
|-----|------|---|---|----|-----|---------------------|
| L15 | 6821 | 324/754 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 19:44 |
| L16 | 1413 | 324/757 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/09/25 20:20 |
| S1 | 1 | "20070040245" | US-PGPUB; USPAT | OR | OFF | 2009/09/22 21:51 |
| S2 | 49 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (via or open\$3 or hole) and elastic near polymer | USPAT | OR | ON | 2009/09/23 19:18 |
| S3 | 385 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (via or open\$3 or hole) and elastic near (polymer or layer or film) | USPAT | OR | ON | 2009/09/23 19:24 |
| S4 | 336 | S3 not S2 | USPAT | OR | ON | 2009/09/23 19:25 |
| S5 | 3880 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic) with (via or open\$3 or hole) and elastic with (polymer or layer or film or insulat\$3 or dielectric) | USPAT | OR | ON | 2009/09/23 19:54 |
| S6 | 212 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic) with (via or open\$3 or hole) and elastic with (polymer or layer or film or insulat\$3 or dielectric) and anisotropica\$3 | USPAT | OR | ON | 2009/09/23 19:54 |

| | | | | | | |
|-----|------|--|-------|----|----|------------------|
| S7 | 212 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and elastic with (polymer or layer or film or insulat\$3 or dielectric) and anisotropica\$3 | USPAT | OR | ON | 2009/09/23 19:55 |
| S8 | 6880 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 | USPAT | OR | ON | 2009/09/23 19:55 |
| S9 | 1412 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) | USPAT | OR | ON | 2009/09/23 19:55 |
| S10 | 0 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and big\$3 near (open \$3 or diameter) | USPAT | OR | ON | 2009/09/23 20:02 |
| S11 | 0 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and (big\$3 or lager) with (open\$3 or diameter) | USPAT | OR | ON | 2009/09/23 20:03 |

| | | | | | | |
|-----|------|---|-------|----|----|---------------------|
| S12 | 0 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and (big or bigger or lager) with (open\$3 or diameter) | USPAT | OR | ON | 2009/09/23 20:03 |
| S13 | 0 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) and (big or bigger or lager) with (open\$3 or hole or via) near (surface or side or diameter) | USPAT | OR | ON | 2009/09/23 20:04 |
| S14 | 1412 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) | USPAT | OR | ON | 2009/09/23 20:04 |
| S15 | 17 | (semiconductor or die or dice or chip or Ic) and (elastic or elastomer) with (via or open\$3 or hole) and anisotropica\$3 near (sheet or layer or film) | USPAT | OR | ON | 2009/09/23 20:29 |
| S16 | 62 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with anisotropica\$3 | USPAT | OR | ON | 2009/09/23 20:30 |
| S17 | 1 | "5622896".pn. | USPAT | OR | ON | 2009/09/23 20:36 |
| S18 | 1 | "5622896".pn. and solvent with ketone | USPAT | OR | ON | 2009/09/23 20:37 |

| | | | | | | |
|-----|-----|---|---------------------------|----|-----|---------------------|
| S19 | 4 | ("20050146336" "6297652" "6720787").PN. OR ("7038471").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/23 20:43 |
| S20 | 8 | ("5903162" "5973505" "6133744" "6540527").PN. OR ("6906541").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/23 20:45 |
| S21 | 151 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with anisotropic\$4 | USPAT | OR | ON | 2009/09/23 20:51 |
| S22 | 89 | S21 not S16 | USPAT | OR | ON | 2009/09/23 20:51 |
| S23 | 2 | "20020191406" | US-PGPUB; USPAT | OR | ON | 2009/09/23 20:54 |
| S24 | 105 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (made or form\$2) with (elastic or elastomer) and (via or open\$3 or hole) with anisotropic \$4 | USPAT | OR | ON | 2009/09/23 21:05 |
| S25 | 584 | (semiconductor or die or dice or chip or Ic) and flexible with (base or film or layer) and (via or open\$3 or hole) with anisotropic\$4 | USPAT | OR | ON | 2009/09/23 21:07 |
| S26 | 541 | S25 not S21 | USPAT | OR | ON | 2009/09/23 21:07 |
| S27 | 12 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with (conduct\$3 near paste) and anisotropic \$4 | USPAT | OR | ON | 2009/09/23 21:45 |

| | | | | | | |
|-----|-----|---|-------|----|----|------------------|
| S28 | 48 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with (conduct\$3 near (paste or particles)) and anisotropic\$4 | USPAT | OR | ON | 2009/09/23 21:46 |
| S29 | 48 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with (conduct\$3 near (paste or particles or powder)) and anisotropic\$4 | USPAT | OR | ON | 2009/09/23 21:46 |
| S30 | 120 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer or flexible) and (via or open\$3 or hole) with (conduct\$3 near (paste or particles or powder)) and anisotropic\$4 | USPAT | OR | ON | 2009/09/23 21:49 |
| S31 | 72 | S30 not S29 | USPAT | OR | ON | 2009/09/23 21:49 |
| S32 | 62 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal\$3) with (paste or particles or powder)) and anisotropic\$4 | USPAT | OR | ON | 2009/09/23 21:52 |

| | | | | | | |
|-----|-----|---|------------------------|----|-----|------------------|
| S33 | 76 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal\$3) with (paste or particles or powder)) and anisotropic\$4 | USPAT | OR | ON | 2009/09/23 21:57 |
| S34 | 14 | S33 not S32 | USPAT | OR | ON | 2009/09/23 21:58 |
| S35 | 6 | ("20040091687" "6359235" "6512182" "6680441" "6928726" "7022399").PN. OR ("7287321").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/23 22:00 |
| S36 | 215 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal\$3) with (paste or particles or powder)) | USPAT | OR | ON | 2009/09/23 22:05 |
| S37 | 171 | S36 not S21 | USPAT | OR | ON | 2009/09/23 22:05 |
| S38 | 125 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 | USPAT | OR | ON | 2009/09/24 14:13 |
| S39 | 14 | ("5140405" "5162613" "5975915").PN. OR ("6690564").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/24 14:35 |
| S40 | 1 | "20020061401" | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/24 14:38 |

| | | | | | | |
|-----|----|---|--------------------|----|----|---------------------|
| S41 | 1 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (elastic or elastomer) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 and "20020061401" | US-PGPUB | OR | ON | 2009/09/24 14:39 |
| S45 | 12 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (silicon near rubber) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 | US-PGPUB | OR | ON | 2009/09/24 17:28 |
| S46 | 19 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric or base or substrate or layer or film) with (silicon near rubber) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 | US-PGPUB; USPAT | OR | ON | 2009/09/24 17:28 |
| S47 | 0 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 and (via or open\$3 or hole) with slop | USPAT | OR | ON | 2009/09/24 18:37 |

| | | | | | | |
|-----|----|--|------------------------|----|-----|------------------|
| S48 | 3 | (semiconductor or die or dice or chip or Ic) and (insulat\$3 or dielectric) and (via or open\$3 or hole) with ((conduct\$3 or metal \$3) with (paste or particles or powder)) and anisotropi\$4 and (via or open\$3 or hole) with (big or bigger or larger) near (surface or side) | USPAT | OR | ON | 2009/09/24 18:38 |
| S49 | 1 | "20020071077" | US-PGPUB; USPAT | OR | ON | 2009/09/24 19:13 |
| S50 | 6 | stack\$3 near (semiconductor or die or dice or IC or chip) and (middle or center) near (semiconductor or die or dice or IC or chip) with (across) with (pattern or metal \$3 or circuit) | USPAT | OR | ON | 2009/09/25 13:25 |
| S51 | 57 | stack\$3 near (semiconductor or die or dice or IC or chip) and (middle or center) near (semiconductor or die or dice or IC or chip) with (pattern or metal\$3 or circuit) | USPAT | OR | ON | 2009/09/25 13:26 |
| S52 | 46 | stack\$3 near (semiconductor or die or dice or IC or chip) and relay with (pads or finger or pattern or circuit) | USPAT | OR | ON | 2009/09/25 13:28 |
| S54 | 11 | ("5012323" "5347159" "5347428" "5422435" "5495398" "5767570" "5903049" "5905639" "5976911" "6133637").PN. OR ("6958532").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/25 13:37 |

| | | | | | | |
|-----|-----|---|---------------------------|----|-----|---------------------|
| S55 | 0 | stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit) | USPAT | OR | ON | 2009/09/25 13:48 |
| S56 | 649 | stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit) | USPAT | OR | ON | 2009/09/25 13:48 |
| S57 | 1 | stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit) and relay\$3 with wir\$3 | USPAT | OR | ON | 2009/09/25 13:49 |
| S58 | 10 | stack\$3 near (semiconductor or die or dice or IC or chip) and cross\$3 with (pads or finger or pattern or circuit) and relay\$3 with wir\$3 | USPAT | OR | ON | 2009/09/25 13:49 |
| S59 | 3 | ("6037661" "6410987").PN. OR ("6798071").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/25 13:52 |
| S60 | 46 | ("5422435" "6005778").PN. OR ("6215182").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/25 13:52 |
| S61 | 14 | stack\$3 near (semiconductor or die or dice or IC or chip) and edge with (pads or finger or pattern or circuit) and relay\$3 with wir\$3 | USPAT | OR | ON | 2009/09/25 13:54 |
| S62 | 461 | stack\$3 near (semiconductor or die or dice or IC or chip) and across\$3 with (pads or finger or pattern or circuit) and wir\$3 | USPAT | OR | ON | 2009/09/25 13:54 |

| | | | | | | |
|-----|------|---|---------------------------|----|-----|---------------------|
| S63 | 142 | stack\$3 near (semiconductor or die or dice or IC or chip) and linear with (pads or finger or pattern or circuit) and wir\$3 | USPAT | OR | ON | 2009/09/25 13:58 |
| S64 | 35 | ("20030038378" "4341594" "4803147" "4948754" "5049980" "5323060" "5366906" "5384488" "5506756" "5554887" "5672912" "5677576" "5683942" "5814894" "5834844" "5844304" "5851911" "5886415" "5925931" "5971253" "5977641" "6043109" "6072236" "6117539" "6181569" "6212767" "6228687" "6255737" "6294407" "6376904" "6534853" "6573609" "6590292").PN. OR ("6987325").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/25 14:03 |
| S65 | 2667 | stack\$3 near (semiconductor or die or dice or IC or chip) and (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) with (semiconductor or die or dice or IC or chip) | USPAT | OR | ON | 2009/09/25 14:05 |

| | | | | | | |
|-----|------|---|---------------------------|----|-----|---------------------|
| S66 | 2090 | stack\$3 near (semiconductor or die or dice or IC or chip) and (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) with (semiconductor or die or dice or IC or chip) and wir\$3 | USPAT | OR | ON | 2009/09/25 14:05 |
| S67 | 460 | stack\$3 near (semiconductor or die or dice or IC or chip) and (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) with (semiconductor or die or dice or IC or chip) and wir\$3 and (cross \$3 or across\$3) with (redistribut\$3 or redirect\$3 or rerout\$3 or interposer or interconnect\$3) | USPAT | OR | ON | 2009/09/25 14:06 |
| S68 | 14 | ("20050172894" "20060267173" "5012323" "5206188" "5285104" "5299097" "5495398" "6376904" "6441495" "6472758" "6514794" "6621155" "6843421" "6900528").PN. OR ("7592691").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/09/25 14:07 |

9/ 25/ 09 8:25:28 PM

C:\ Documents and Settings\ cchu\ My Documents\ EAST\ Workspaces\ 10579342.wsp